



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-12-18
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RQWQ*UW71AD6	A	Z6HA	2015-12-18
Amount	UoM	Unit type	ST ECOPACK Grade	
17.10	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x1	10	No lead	
Comment	Package: VDFPN 3x3x1.0 10 PITCH 0.50; MDF valid for STEF12PUR; STEF12PUR/EMC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RQWQ*UW71AD6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	1.734	mg	supplier	die	Silicon (Si)	7440-21-3		1.642	mg	946943	96023
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	5767	585
				supplier	metallization	Titanium (Ti)	7440-32-6		0.024	mg	13841	1404
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	4614	468
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	16724	1696
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	577	58
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.006	mg	3460	351
				supplier	polymer die coating	PIXL Gamma-butyrolactone	96-48-0		0.014	mg	8074	819
				supplier	alloy	Copper (Cu)	7440-50-8		10.017	mg	995132	585789
Leadframe	Copper & its alloys	10.066	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.005	mg	497	292
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.008	mg	795	468
				supplier	metallization	Nickel (Ni)	7440-02-0		0.033	mg	3278	1930
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	199	117
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	99	58
				supplier	glue	Silver (Ag)	7440-22-4		0.252	mg	684783	14737
Die attach	Other inorganic materials	0.368	mg	supplier	glue	methylene diacrylate	42594-17-2		0.092	mg	250000	5380
				supplier	glue	Dicyclopentenloxyethyl methacrylate	68586-19-6		0.011	mg	29891	643
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.011	mg	29891	643
				supplier	glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.002	mg	5435	117
				supplier	glue or tape	Silver (Ag)	7440-22-4		0.297	mg	818182	17368
Die attach 2	Other inorganic materials	0.363	mg	supplier	glue or tape	acrylate	65983-31-5		0.022	mg	60606	1287
				supplier	glue or tape	poly butadiene derivative	Proprietary		0.022	mg	60606	1287
				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.011	mg	30303	643
				supplier	glue or tape	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.007	mg	19284	409
				supplier	glue or tape	Butadiene copolymer	68891-50-9		0.004	mg	11019	234
Bonding wires	Precious metals	0.180	mg	supplier	wire	Gold (Au)	7440-57-5		0.127	mg	705556	7427
				supplier	wire	Copper (Cu)	7440-50-8		0.053	mg	294444	3099
Encapsulation	Other Organic Materials	4.389	mg	supplier	mold compound	Silica, vitreous	60676-86-0		4.064	mg	925951	237661
				supplier	mold compound	epoxy resin	85954-11-6		0.176	mg	40100	10292
				supplier	mold compound	phenol resin	26834-02-6		0.132	mg	30075	7719
				supplier	mold compound	carbon black	1333-86-4		0.017	mg	3873	994